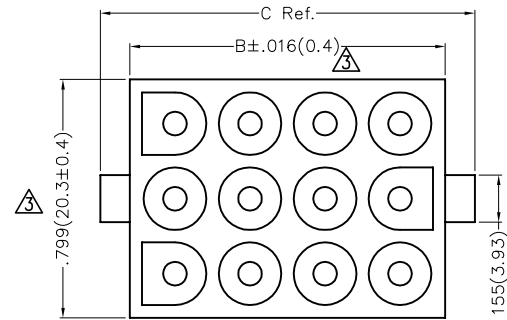


1 2 3 4 5 6 7 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△1	Size change	10/JUN/22	MATT	CHERRY
2	△2	Flammability Change	02/AUG/23	MATT	LEO
3	△3	Update dimensions and tolerances	31/MAR/25	MATT	LEO

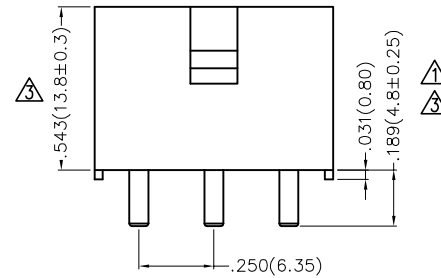
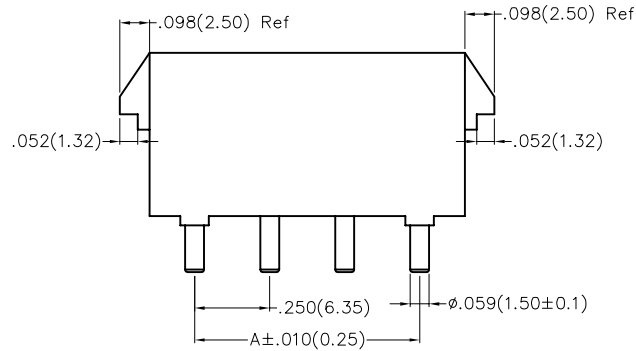


Electrical

Current Rating: 13A AC(rms)/DC
 Voltage Rating: 300V AC(rms)/DC
 Contact Resistance: 20 mΩ Max
 Insulation Resistance: 1000 MΩ MIN
 Withstanding Voltage: 1500V AC r.m.s
 Temperature Range—Operating: -25°C~+85°C

Material and Plating

Housing: PA66(UL 94V-2) △2
 Contact Pin: Brass
 Plating: Tin Plated

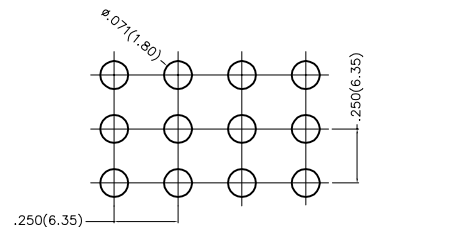


Circuits (n)	Part No.	Dimensions(in/mm)		
		A	B △3	C
9	FWF63503-T09S22TB	.500(12.70)	.799(20.30)	.996(25.30)
12	FWF63503-T12S22TB	.750(19.05)	1.047(26.60)	1.248(31.70)
15	FWF63503-T15S22TB	1.00(25.40)	1.295(32.90)	1.496(38.00)

Ordering Information

FWF 635 03 — T XX S 2 2 T B
 1 2 3 4 5 6 7 8 9 10

1 Category FWF-Wafer	2 Series Number 635-Pitch6.35mm	3 Distinction No. 03	4 Row Option T-Triple Row	5 Circuits XX	6 Entry Angle S-180° Vertical
7 Plating 2-Tin Plated	8 Material-Resin 2-PA66	9 Color-Resin T-Transparent	10 Packaging B-PE Bag		



Recommended P.C.Board Layout

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF63503-TXXS22TB	ITEM NO. FWF63503	Building Technology Cornerstone
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X'±5'	CHECKED BY JACOB	DATE 28/JUN/13	TITLE Wire to Board (Wafer) Pitch 6.35mm 180° Vertical (DIP)		
SCALE 5:1	SIZE A4	X.XX±.006(0.15) .XX'±1'	DRAWN BY CHERRY	DATE 28/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

1 2 3 4 5 6 7 8